Layer	Name	Material	Thickness
	Top Overlay		
	Top Solder	SM-002	0.025mm
	Top Surface Finish	Nickel, Gold	0.004mm
1	Top Layer	CF-004	0.035mm
	Dielectric1	PP-008	0.079mm
2	Layer 2	CF-004	0.035mm
	Core	Core-041	0.889mm
3	Layer 3	CF-004	0.035mm
	Dielectric2	PP-008	0.079mm
4	Bottom Layer	CF-004	0.035mm
	Bottom Surface Finish	Nickel, Gold	0.004mm
	Bottom Solder	SM-002	0.025mm
	Bottom Overlay		
Total board thickness:			1.245mm

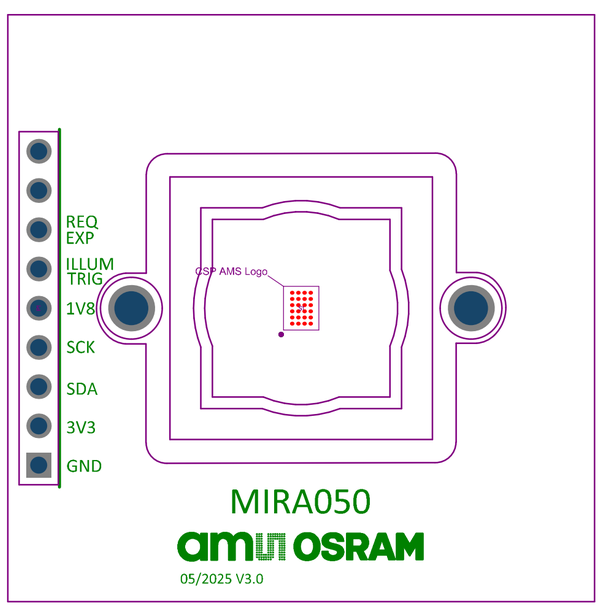
SPECIFICATIONS

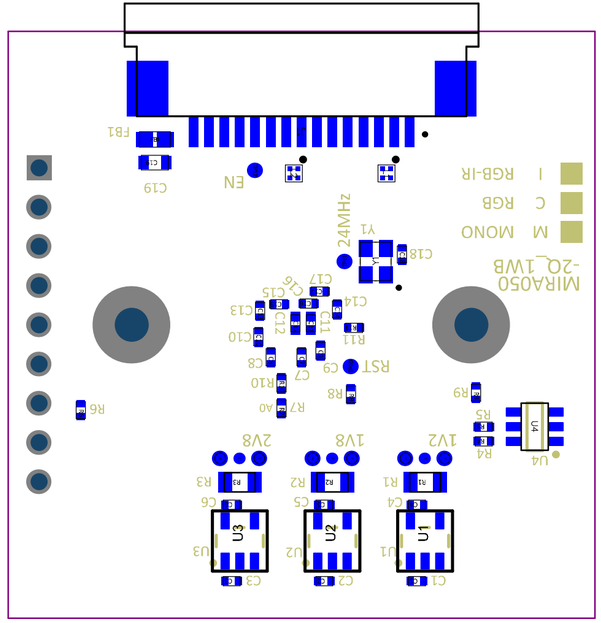
FINISHED BOARD TOTAL THICKNESS IS 1.2MM (1.0 to 1.6 acceptable)

micro vias TOP–L1; first/last dielectric approx 80um for impedance

all thru VIAS plugged, filled, tented

SILKSCREEN COLOR: WHITE (Yellow acceptable)
SOLDER MASK COLOR: GREEN (other dark acceptable)
BOARD FINISH: ENIG or ENEPIG





SPECIFICATIONS

Layer	Name	Material	Thickness
	Top Overlay		
	Top Solder	SM-005	0.025mm
	Top Surface Finish	Nickel, Gold	0.004mm
1	Top Layer	CF-004	0.035mm
	Dielectric	PP-008	0.075mm
5	Layer 5	CF-004	0.035mm
	Core	Core-041	0.889mm
3	Layer 3	CF-004	0.035mm
	Dielectric	PP-008	0.075mm
4	Bottom Layer	CF-004	0.035mm
	Bottom Surface Finish	Nickel, Gold	0.004mm
	Bottom Solder	SM-005	0.025mm
	Bottom Overlay		

Total board thickness: 1.574mm

BOARD FINISH: ENIG or ENEPIG
SOLDER MASK COLOR: GREEN (other dark acceptable)
SILKSCREEN COLOR: WHITE (yellow acceptable)

all furn VIAS bludged, filled, fenfed

micro vias TOP-L1: firstlayer dielectric approx 80um for impedance

FINISHED BOARD TOTAL THICKNESS IS 1.5MM (1.0 to 1.6 acceptable)